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Kind regards,

Team Nexperia



BAT165A

40 V, 0.75 A medium power Schottky barrier rectifier

2 May 2016

Product data sheet

1. General description

Medium power Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a very small SOD323 (SC-76) Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Forward current: $I_F \leq 0.75$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage typ. $V_F = 640$ mV
- Low reverse current typ. $I_R = 1.5$ μ A
- Very small SMD plastic package
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption application
- Automotive applications

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 93$ °C; $\delta = 1$	-	-	0.75	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	40	V
V_F	forward voltage	$I_F = 750$ mA; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C	-	640	740	mV
I_R	reverse current	$V_R = 40$ V; pulsed; $T_j = 25$ °C	-	1.5	8	μ A
		$V_R = 40$ V; pulsed; $T_j = 65$ °C	-	30	900	μ A





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4. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 SOD323	 sym001
2	A	anode		

5. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT165A	SOD323	plastic surface-mounted package; 2 leads	SOD323

6. Marking

Table 4. Marking codes

Type number	Marking code
BAT165A	2G

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	40	V
I_F	forward current	$T_{sp} \leq 93\text{ }^{\circ}\text{C}$; $\delta = 1$		-	0.75	A
$I_{F(AV)}$	average forward current	50 Hz $\leq f \leq$ 60 Hz; $T_{amb} \leq 93\text{ }^{\circ}\text{C}$; pulsed sinusoidal		-	0.5	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; square wave		-	8	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[1]	-	380	mW
			[2]	-	555	mW
T_j	junction temperature			-	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	150	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	150	$^{\circ}\text{C}$

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

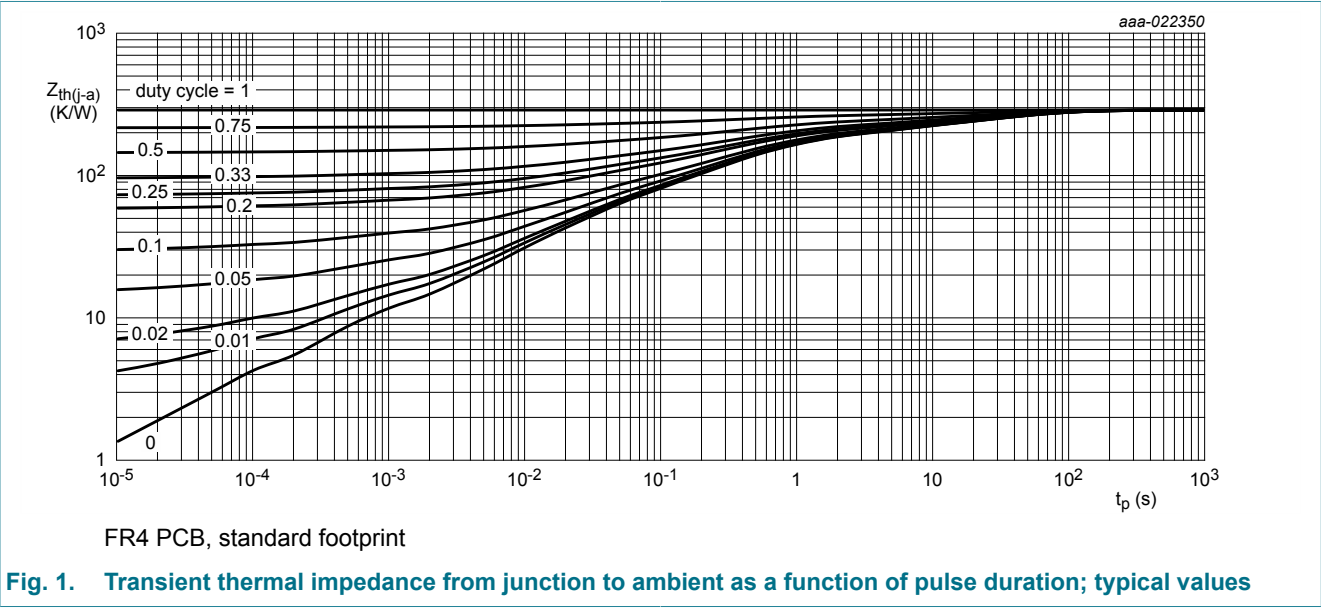
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

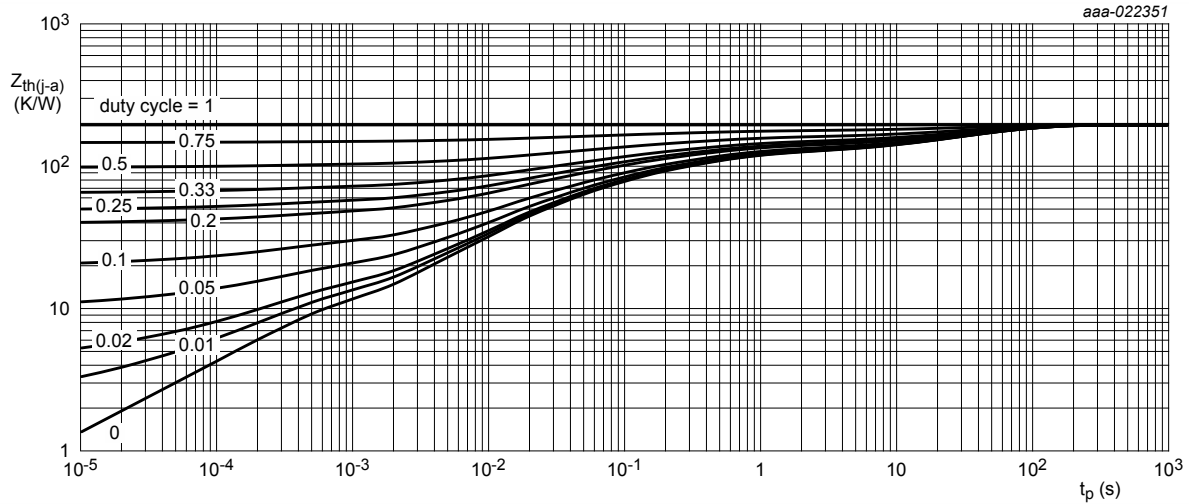
8. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1][2]	-	-	330	K/W
			[1][3]	-	-	225	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[4]	-	-	45	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.





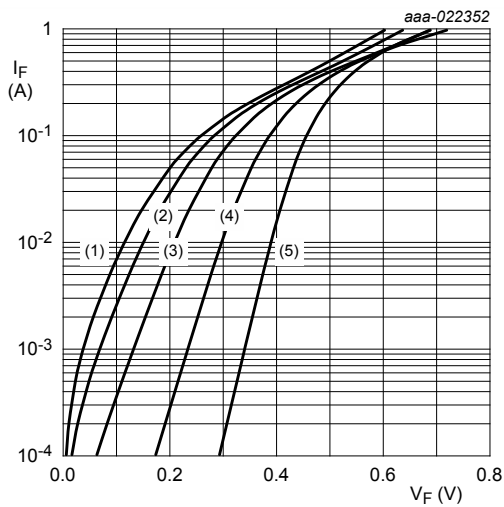
FR4 PCB, mounting pad for cathode 1 cm²

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

9. Characteristics

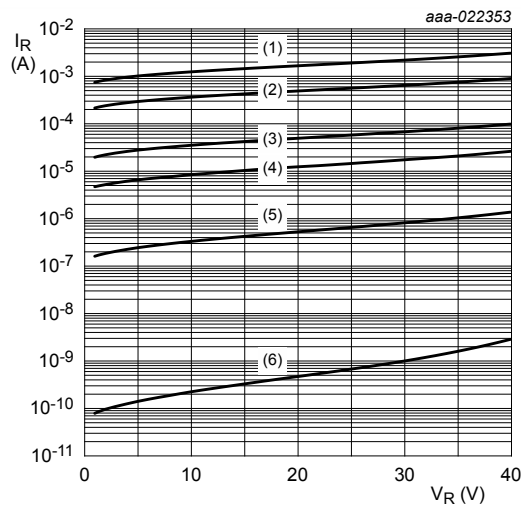
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$; pulsed	40	-	-	V
V_F	forward voltage	$I_F = 10 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$	-	300	380	mV
		$I_F = 100 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$	-	390	470	mV
		$I_F = 250 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$	-	455	540	mV
		$I_F = 500 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$	-	550	640	mV
		$I_F = 750 \text{ mA}$; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ } ^\circ\text{C}$	-	640	740	mV
I_R	reverse current	$V_R = 30 \text{ V}$; pulsed; $T_j = 25 \text{ } ^\circ\text{C}$	-	1	5	μA
		$V_R = 40 \text{ V}$; pulsed; $T_j = 25 \text{ } ^\circ\text{C}$	-	1.5	8	μA
		$V_R = 40 \text{ V}$; pulsed; $T_j = 65 \text{ } ^\circ\text{C}$	-	30	900	μA
		$V_R = 5 \text{ V}$; pulsed; $T_j = 125 \text{ } ^\circ\text{C}$	-	290	700	μA
		$V_R = 40 \text{ V}$; pulsed; $T_j = 125 \text{ } ^\circ\text{C}$	-	1	8	mA
C_d	diode capacitance	$V_R = 10 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ } ^\circ\text{C}$	-	9	12	pF



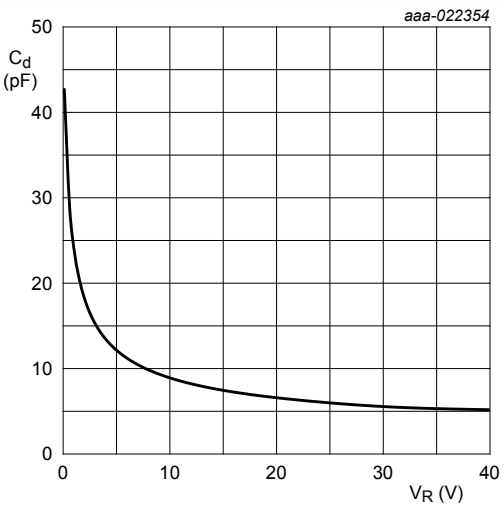
pulsed condition
(1) $T_j = 150^\circ\text{C}$
(2) $T_j = 125^\circ\text{C}$
(3) $T_j = 85^\circ\text{C}$
(4) $T_j = 25^\circ\text{C}$
(5) $T_j = -40^\circ\text{C}$

Fig. 3. Forward current as a function of forward voltage; typical values



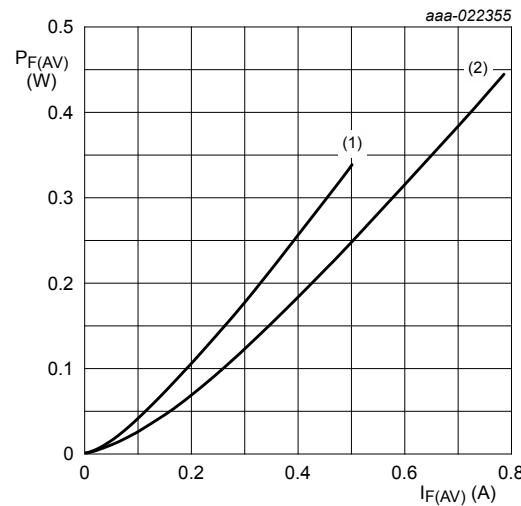
pulsed condition
(1) $T_j = 150^\circ\text{C}$
(2) $T_j = 125^\circ\text{C}$
(3) $T_j = 85^\circ\text{C}$
(4) $T_j = 65^\circ\text{C}$
(5) $T_j = 25^\circ\text{C}$
(6) $T_j = -40^\circ\text{C}$

Fig. 4. Reverse current as a function of reverse voltage; typical values



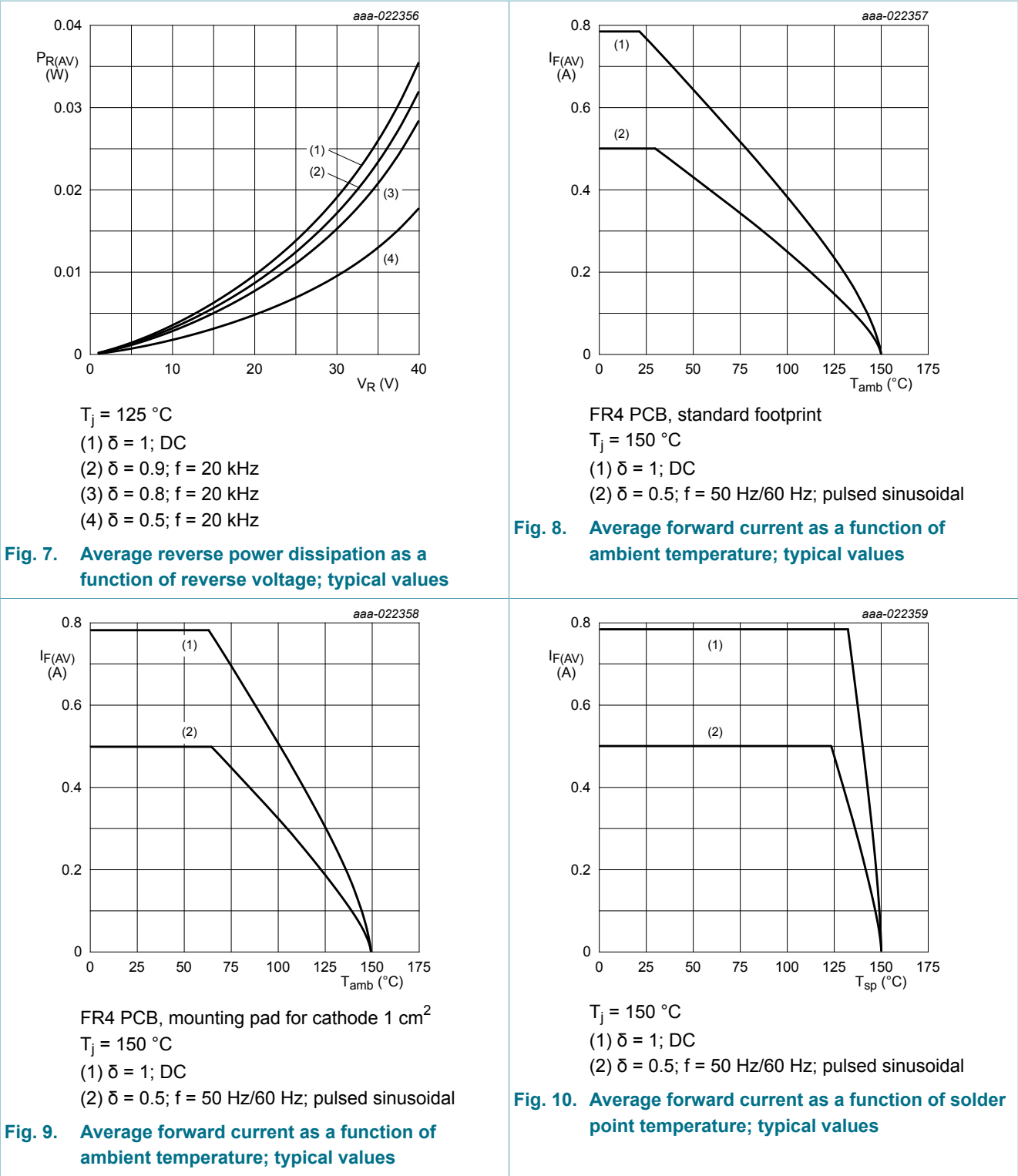
$f = 1\text{ MHz}$; $T_{\text{amb}} = 25^\circ\text{C}$

Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150^\circ\text{C}$
(1) $\delta = 0.5$ sinusoidal
(2) $\delta = 1$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



10. Test information

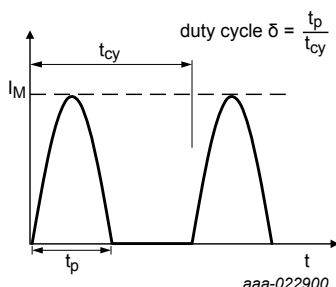


Fig. 11. Duty cycle definition: sinusoidal

The current ratings for the sinusoidal waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times 0.3183$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta/2}$ with I_{RMS} defined as RMS current.

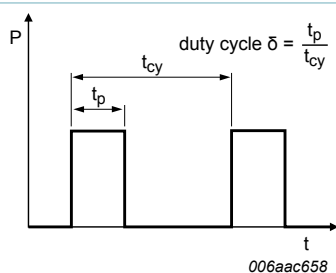


Fig. 12. Duty cycle definition: square wave

10.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

11. Package outline

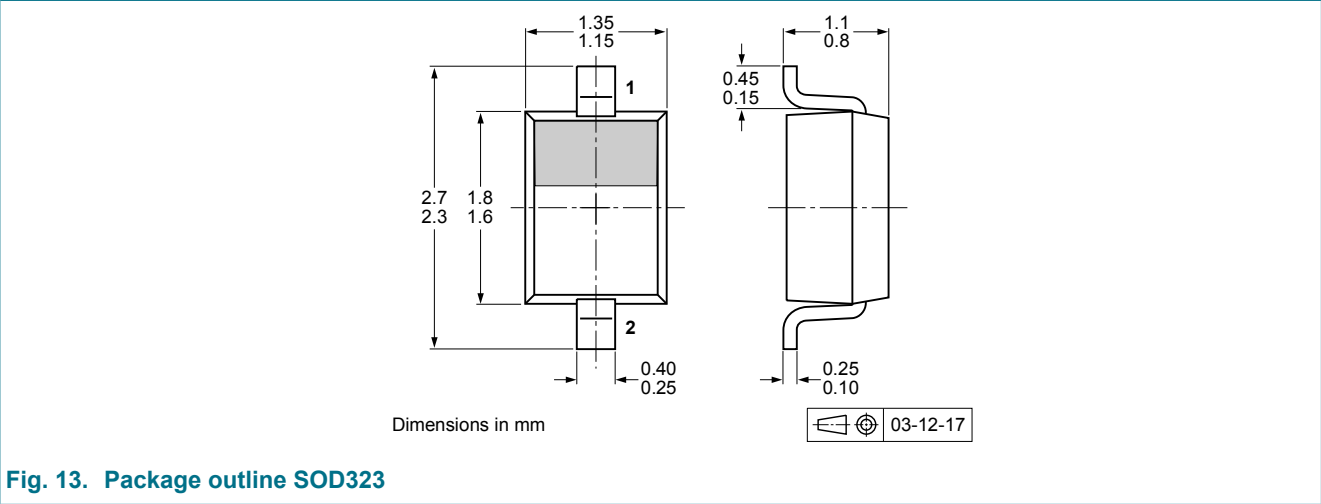


Fig. 13. Package outline SOD323

12. Soldering

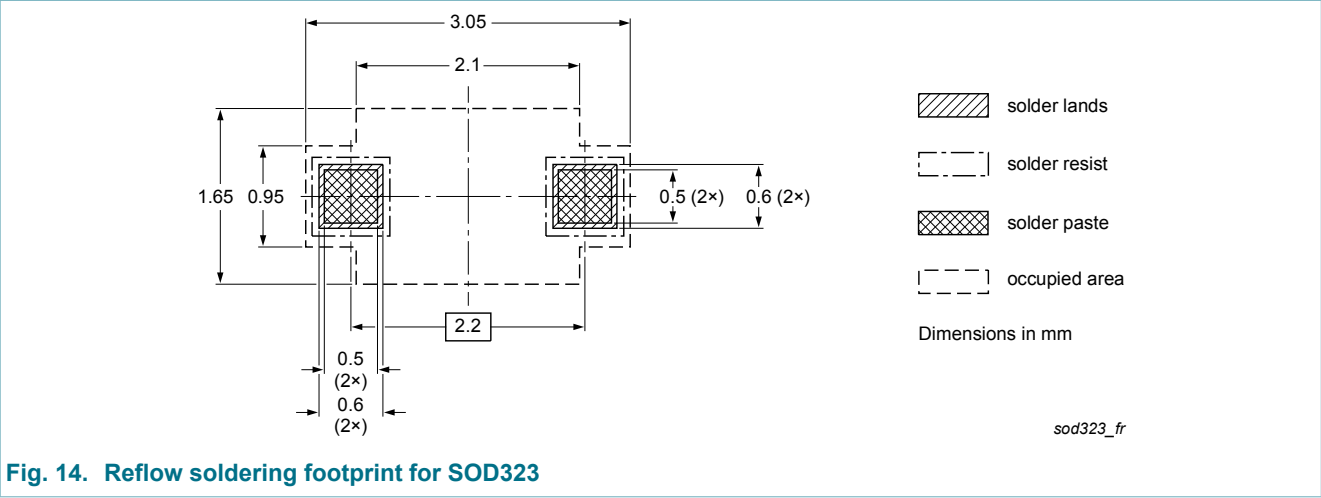
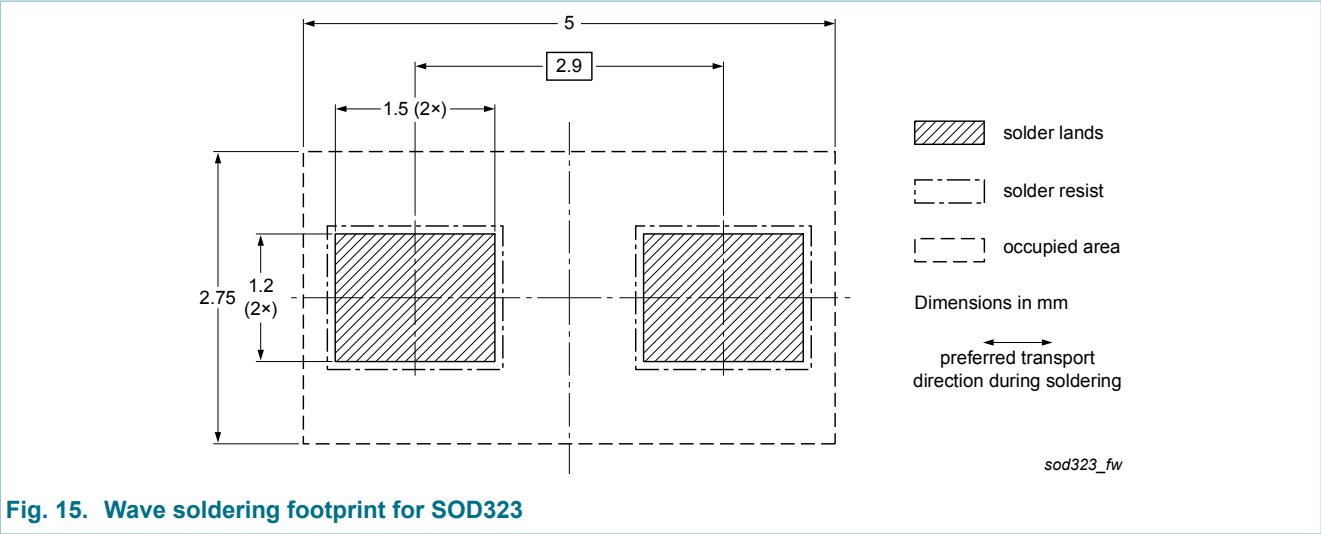


Fig. 14. Reflow soldering footprint for SOD323



13. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BAT165A v.1	20160502	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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